

REMARKS

This amendment is submitted to correct a minor error in claim 46. No new matter has been added. A copy of the amended portion of claim 46, with changes marked therein, is attached and entitled "Version with markings to show changes made."

Accordingly, entry of the amendment is requested.

Respectfully submitted,

Kazuto NISHIDA et al.

By: Michael S. Huppert  
Michael S. Huppert  
Registration No. 40,268  
Attorney for Applicants

MSH/kjf  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
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Version with Markings to  
Show Changes Made

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Version with Markings to  
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46.(Amended)

An electronic component mounting method comprising:  
mounting an electronic component (1) on a circuit board (4)

while aligning in position an electrode of the electronic component (1) and an electrode (5) of the circuit board (4) in a state in which the electrode (2) of the electronic component (1) has a bump (3, 103) with interposition of an anisotropic conductive layer (10) in which an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a); and

subsequently bonding the electronic component to the circuit board by hardening the insulating resin of the anisotropic conductive layer interposed between the electronic component and the circuit board while correcting warp of the board with a pressure force applied to the electronic component against the circuit board by means of a tool (8) and heat applied from the electronic component side or heat applied from the board side or heat applied from both the electronic component side and the board side, so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

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